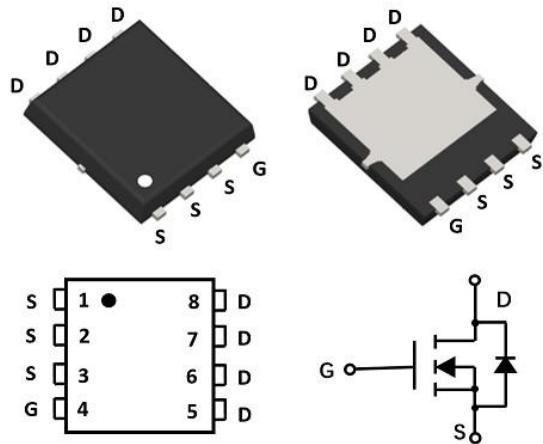


## N-Channel Enhancement Mode Field Effect Transistor

### Product Summary

- $V_{DS}$  60V
- $I_D$  50A
- $R_{DS(ON)}$  (at  $V_{GS}=10V$ ) <10 mohm
- $R_{DS(ON)}$  (at  $V_{GS}=4.5V$ ) <13 mohm
- 100% UIS Tested
- 100%  $\nabla V_{DS}$  Tested

### PDFN5x6-8



### General Description

- Split Gate Trench MOSFET technology
- Excellent package for heat dissipation
- High density cell design for low  $R_{DS(ON)}$

### Applications

- DC-DC Converters
- Power management functions
- Industrial and Motor Drive application

### Absolute Maximum Ratings ( $T_A=25^\circ C$ unless otherwise noted)

Parameter		Symbol	Limit	Unit
Drain-source Voltage		$V_{DS}$	60	V
Gate-source Voltage		$V_{GS}$	$\pm 20$	V
Drain Current (Silicon limited)	Tc=25°C	$I_D$	50	A
	Tc=100°C		15	
Pulsed Drain Current <sup>A</sup>		$I_{DM}$	200	A
Avalanche energy <sup>B</sup>		$E_{AS}$	66	mJ
Total Power Dissipation <sup>C</sup>	Tc=25°C	$P_D$	83	W
	Tc=100°C		28	
Junction and Storage Temperature Range		$T_J, T_{STG}$	-55~+150	°C

### Thermal resistance

Parameter		Symbol	Typ	Max	Units
Thermal Resistance Junction-to-Ambient <sup>D</sup>		$R_{\theta JA}$	10	12	°C/W
Thermal Resistance Junction-to-Ambient <sup>D</sup>	Steady-State		20	30	
Thermal Resistance Junction-to-Case	Steady-State	$R_{\theta JC}$	1.3	1.8	

### Ordering Information (Example)

PREFERRED P/N	PACKING CODE	Marking	MINIMUM PACKAGE(pcs)	INNER BOX QUANTITY(pcs)	OUTER CARTON QUANTITY(pcs)	DELIVERY MODE
PL50N06BGD5	F1	50N06BG	5000	10000	100000	13" reel

## ■ Electrical Characteristics ( $T_J=25^\circ\text{C}$ unless otherwise noted)

Parameter	Symbol	Conditions	Min	Typ	Max	Units
<b>Static Parameter</b>						
Drain-Source Breakdown Voltage	$\text{BV}_{\text{DSS}}$	$V_{\text{GS}}=0\text{V}, I_{\text{D}}=250\mu\text{A}$	60			V
Zero Gate Voltage Drain Current	$I_{\text{DSS}}$	$V_{\text{DS}}=60\text{V}, V_{\text{GS}}=0\text{V}$	$T_J=25^\circ\text{C}$		1	$\mu\text{A}$
			$T_J=55^\circ\text{C}$		5	
Gate-Body Leakage Current	$I_{\text{GSS}}$	$V_{\text{GS}}= \pm 20\text{V}, V_{\text{DS}}=0\text{V}$			$\pm 100$	nA
Gate Threshold Voltage	$V_{\text{GS}(\text{th})}$	$V_{\text{DS}}=V_{\text{GS}}, I_{\text{D}}=250\mu\text{A}$	2.0	2.5	4.0	V
Static Drain-Source On-Resistance	$R_{\text{DS}(\text{ON})}$	$V_{\text{GS}}= 10\text{V}, I_{\text{D}}=20\text{A}$		9.1	10	$\text{m}\Omega$
		$V_{\text{GS}}= 4.5\text{V}, I_{\text{D}}=10\text{A}$		11.5	13	
Diode Forward Voltage	$V_{\text{SD}}$	$I_{\text{s}}=20\text{A}, V_{\text{GS}}=0\text{V}$		0.85	1.3	V
Maximum Body-Diode Continuous Current	$I_{\text{s}}$				50	A
<b>Dynamic Parameters</b>						
Input Capacitance	$C_{\text{iss}}$	$V_{\text{DS}}=35\text{V}, V_{\text{GS}}=0\text{V}, f=1\text{MHz}$		1072		$\text{pF}$
Output Capacitance	$C_{\text{oss}}$			192		
Reverse Transfer Capacitance	$C_{\text{rss}}$			8		
Gate Resistance	$R_g$	$f=1\text{MHz}, \text{Open drain}$		1.6		$\Omega$
<b>Switching Parameters</b>						
Total Gate Charge	$Q_g(10\text{V})$	$V_{\text{DS}}=30\text{V}, I_{\text{D}}=20\text{A}$		34		$\text{nC}$
Total Gate Charge	$Q_g(4.5\text{V})$			15.8		
Gate-Source Charge	$Q_{\text{gs}}$			7.8		
Gate-Drain Charge	$Q_{\text{gd}}$			5.2		
Reverse Recovery Charge	$Q_{\text{rr}}$	$I_f=20\text{A}, di/dt=200\text{A/us}$		36		$\text{ns}$
Reverse Recovery Time	$t_{\text{rr}}$			27		
Turn-on Delay Time	$t_{\text{D(on)}}$			10		
Turn-on Rise Time	$t_r$	$V_{\text{GS}}=10\text{V}, V_{\text{DD}}=30\text{V}, I_{\text{D}}=12\text{A}$ $R_{\text{GEN}}=3\Omega$		36		$\text{ns}$
Turn-off Delay Time	$t_{\text{D(off)}}$			30		
Turn-off fall Time	$t_f$			57		

- A. Repetitive rating; pulse width limited by max. junction temperature.
- B.  $V_{\text{DD}}=50\text{V}, R_g=25\Omega, L=1\text{mH}, I_{\text{AS}}=18\text{A},$ .
- C.  $P_d$  is based on max. junction temperature, using junction-case thermal resistance.
- D. The value of  $R_{\theta JA}$  is measured with the device mounted on 1in2 FR-4 board with 2oz. Copper, in a still air environment with  $T_A=25^\circ\text{C}$ . The Power dissipation  $P_{\text{DSM}}$  is based on  $R_{\theta JA} \leq 10\text{s}$  and the maximum allowed junction temperature of  $150^\circ\text{C}$ . The value in any given application depends on the user's specific board design.

## ■ Typical Performance Characteristics

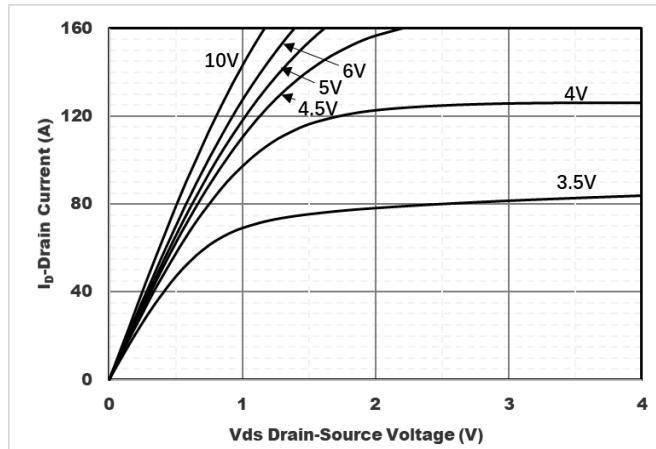


Figure1. Output Characteristics

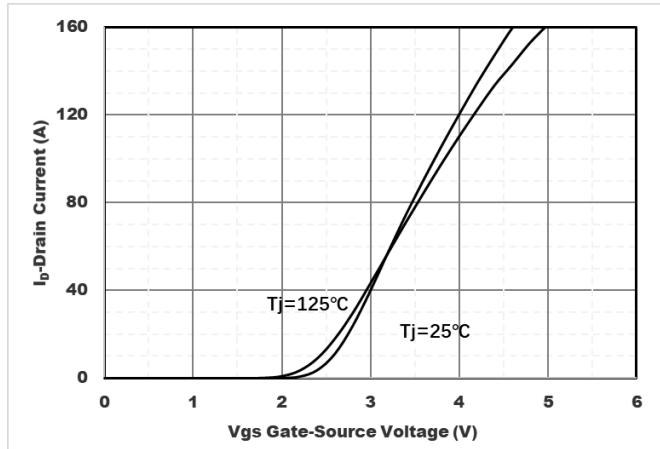


Figure2. Transfer Characteristics

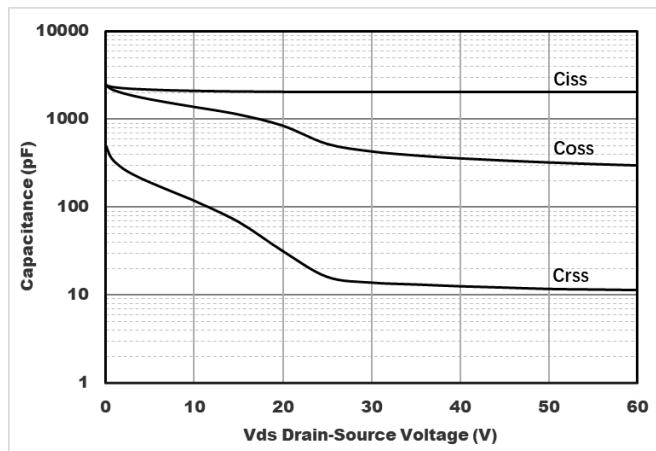


Figure3. Capacitance Characteristics

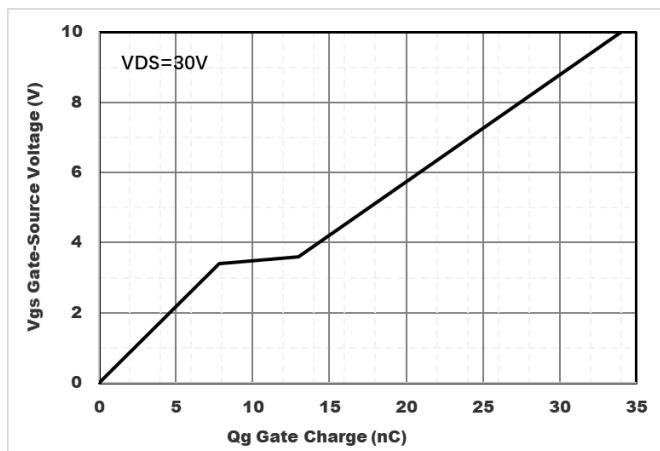


Figure4. Gate Charge

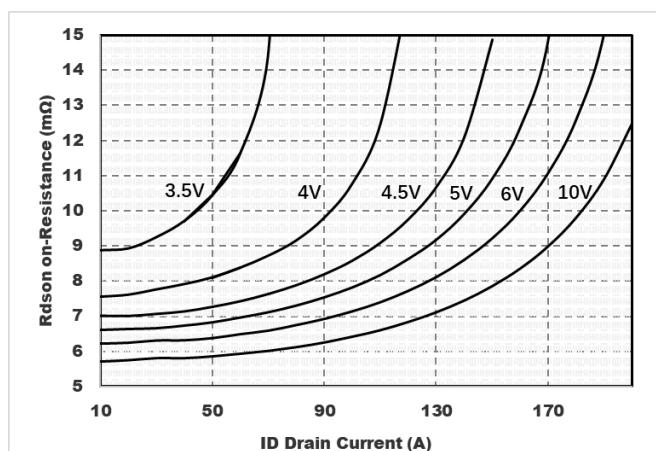


Figure5. Drain-Source on Resistance

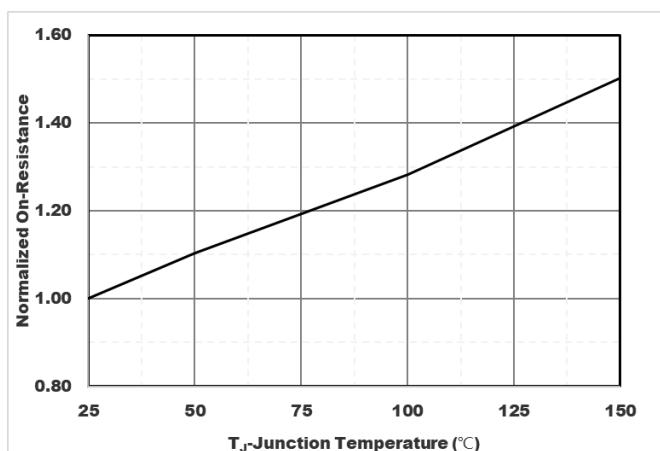


Figure6. Normalized On-Resistance

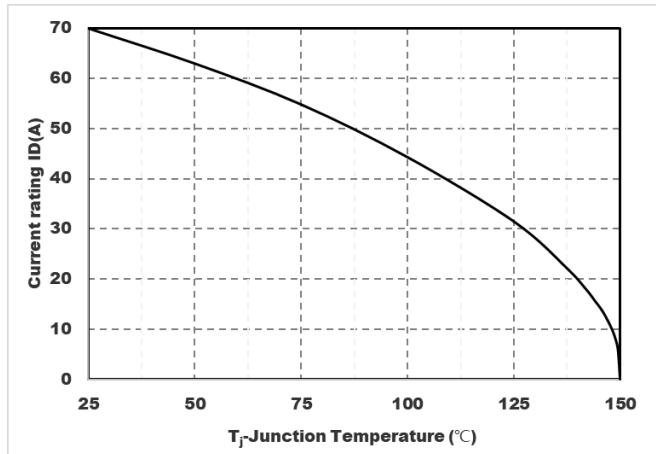


Figure7. Drain current

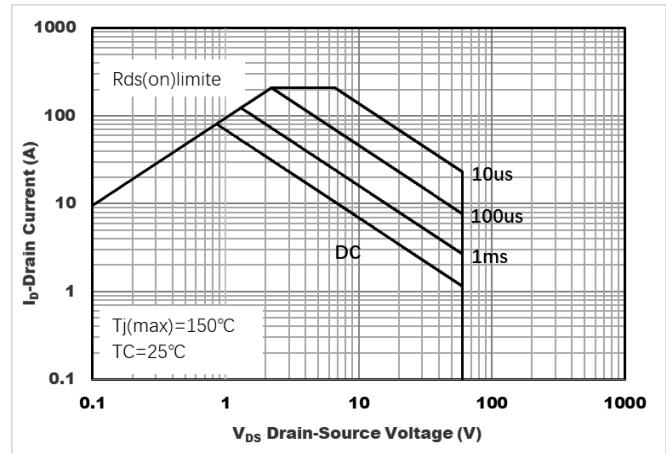


Figure8. Safe Operation Area

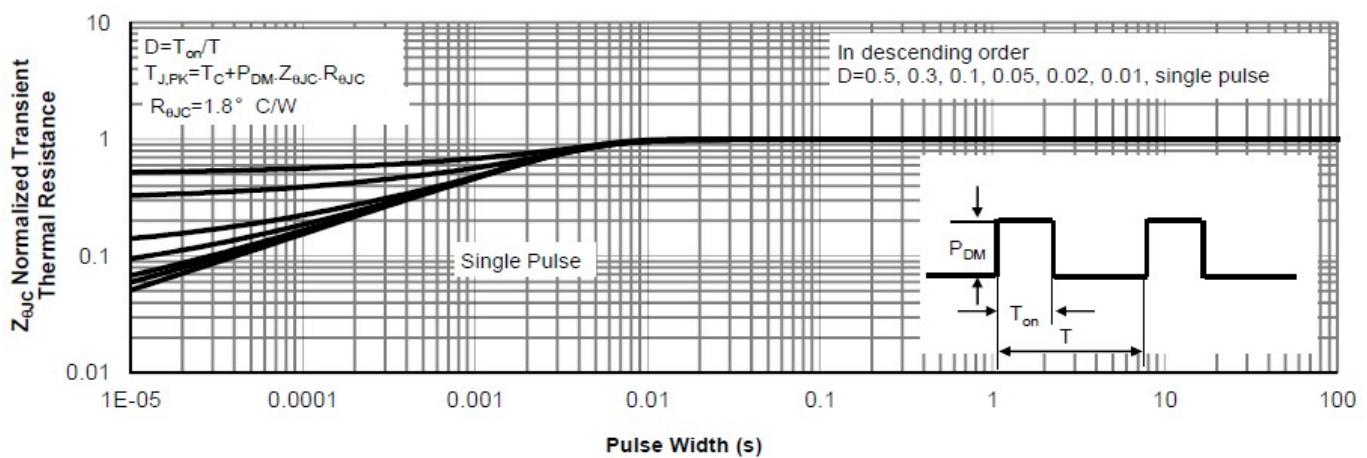
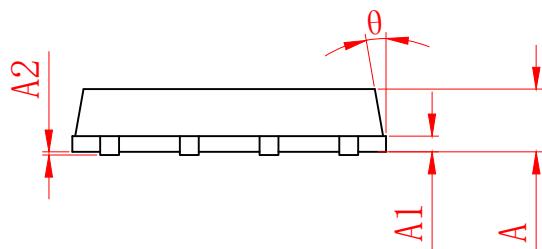
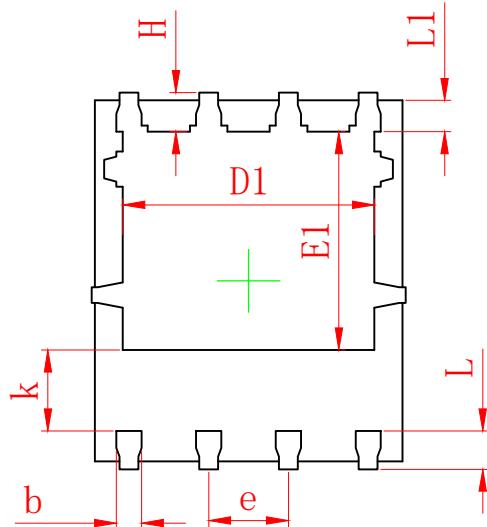
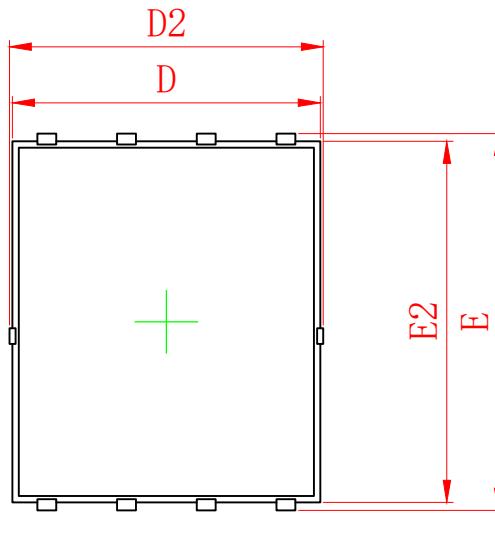


Figure8. Normalized Maximum Transient Thermal Impedance

**■ PDFN5x6-8 Package information**


SYMBOL	MILLIMETER		
	MIN	Typ.	MAX
A	0.900	1.000	1.100
A1	0.254REF.		
A2	0~0.05		
D	4.824	4.900	4.976
D1	3.910	4.010	4.110
D2	4.924	5.000	5.076
E	5.924	6.000	6.076
E1	3.375	3.475	3.575
E2	5.674	5.750	5.826
b	0.350	0.400	0.450
e	1.270TYP.		
L	0.534	0.610	0.686
L1	0.424	0.500	0.576
k	1.190	1.290	1.390
H	0.549	0.625	0.701
θ	8°	10°	12°